

SLG47115V GreenPAK DIP Adapter

This user guide is intended to familiarize new users with the SLG47115V GreenPAK DIP Adapter. It consists of the description of the board, lists its features, shows top and bottom views, as well as the board schematic.

Contents

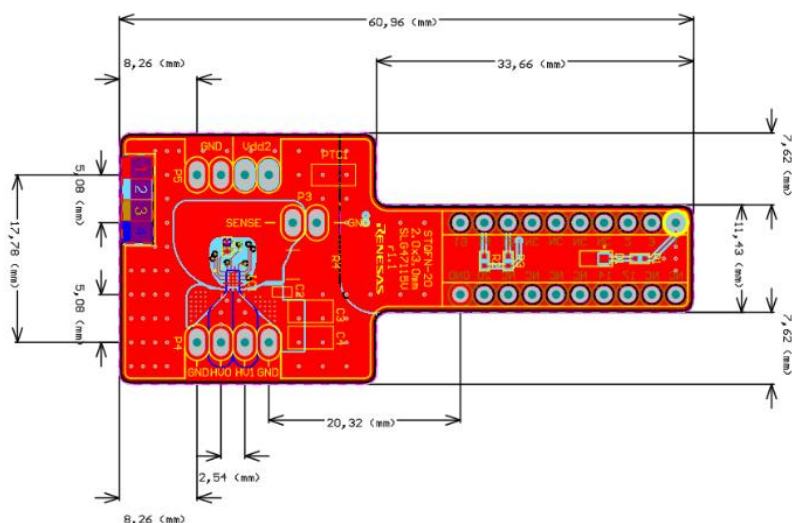
1. Description	1
2. Features	1
3. Top View	2
4. Bottom View	2
5. Board Schematic	3
6. Revision History	3

1. Description

The SLG47115 DIP Adapter is a small PCB that lets you adapt STQFN packages into a DIP footprint. This board can speed up your design prototyping and testing. This small board 0.90x2.20 inch uses 20 pins DIP footprint with 0.3 inch width. You can also use this adapter for prototyping by making STQFN package compatible with solder free breadboards.

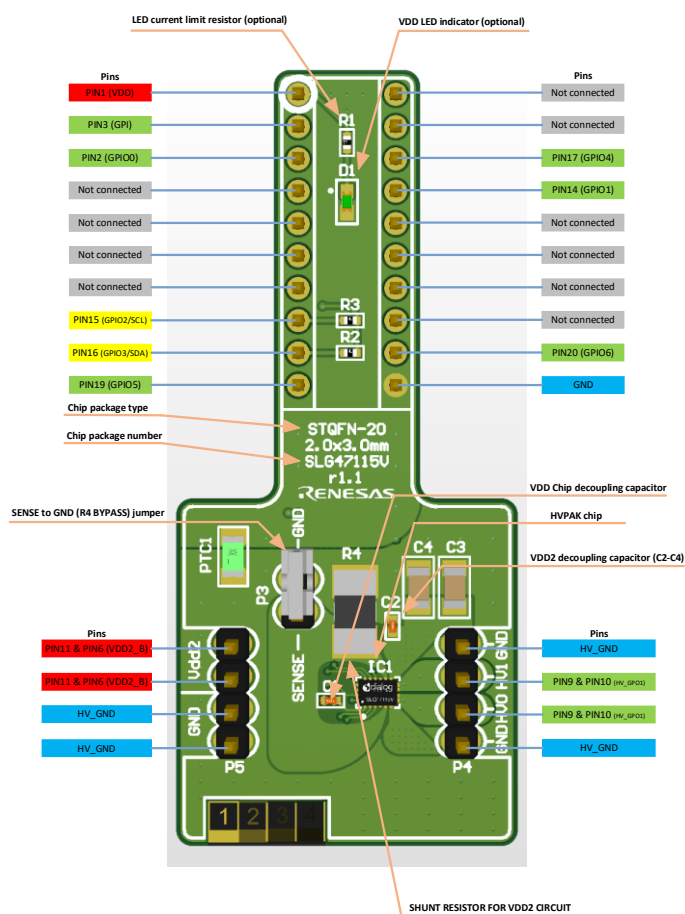
2. Features

- Low cost
- Simplifies prototyping of SMT IC's
- Four high voltage high current output GPOs
- Current up to 2 A per HV GPO
- Current sensing resistors
- Variable current sensing configurations
- Optional V_{DD} LED indicator
- Decoupling capacitor included
- Screw terminals for high voltage and high current lines
- Optional I²C pull-up resistors

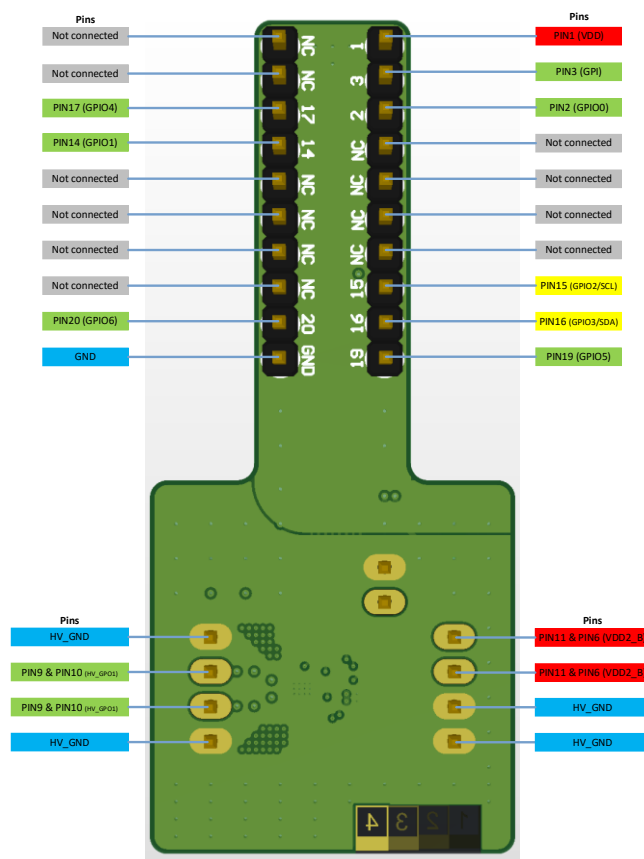


Note 1: All sizes in millimeters (mm).

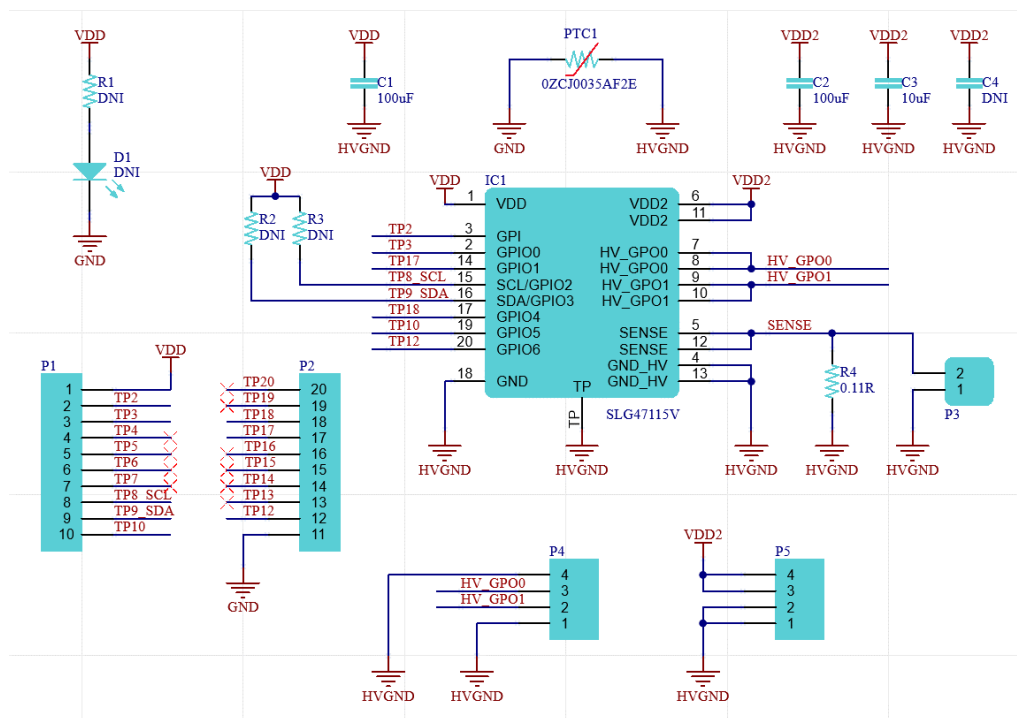
3. Top View



4. Bottom View



5. Board Schematic



6. Revision History

Revision	Date	Description
1.00	May 12, 2022	Initial release.

IMPORTANT NOTICE AND DISCLAIMER

RENESAS ELECTRONICS CORPORATION AND ITS SUBSIDIARIES ("RENESAS") PROVIDES TECHNICAL SPECIFICATIONS AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS OR IMPLIED, INCLUDING, WITHOUT LIMITATION, ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, OR NON-INFRINGEMENT OF THIRD-PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for developers who are designing with Renesas products. You are solely responsible for (1) selecting the appropriate products for your application, (2) designing, validating, and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. Renesas grants you permission to use these resources only to develop an application that uses Renesas products. Other reproduction or use of these resources is strictly prohibited. No license is granted to any other Renesas intellectual property or to any third-party intellectual property. Renesas disclaims responsibility for, and you will fully indemnify Renesas and its representatives against, any claims, damages, costs, losses, or liabilities arising from your use of these resources. Renesas' products are provided only subject to Renesas' Terms and Conditions of Sale or other applicable terms agreed to in writing. No use of any Renesas resources expands or otherwise alters any applicable warranties or warranty disclaimers for these products.

(Disclaimer Rev.1.01)

Corporate Headquarters

TOYOSU FORESIA, 3-2-24 Toyosu,
Koto-ku, Tokyo 135-0061, Japan
www.renesas.com

Contact Information

For further information on a product, technology, the most up-to-date version of a document, or your nearest sales office, please visit www.renesas.com/contact-us/.

Trademarks

Renesas and the Renesas logo are trademarks of Renesas Electronics Corporation. All trademarks and registered trademarks are the property of their respective owners.